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Understanding [Embedded - CPLDs \(Complex Programmable Logic Devices\)](#)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details

Product Status	Not For New Designs
Programmable Type	In System Programmable
Delay Time tpd(1) Max	10 ns
Voltage Supply - Internal	4.5V ~ 5.5V
Number of Logic Elements/Blocks	-
Number of Macrocells	256
Number of Gates	-
Number of I/O	128
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	208-BFQFP
Supplier Device Package	208-PQFP (28x28)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/m4a5-256-128-10yni

Product-Term Array

The product-term array consists of a number of product terms that form the basis of the logic being implemented. The inputs to the AND gates come from the central switch matrix (Table 5), and are provided in both true and complement forms for efficient logic implementation.

Table 5. PAL Block Inputs

Device	Number of Inputs to PAL Block
M4A3-32/32 and M4A5-32/32	33
M4A3-64/32 and M4A5-64/32	33
M4A3-64/64	33
M4A3-96/48 and M4A5-96/48	33
M4A3-128/64 and M4A5-128/64	33
M4A3-192/96 and M4A5-192/96	34
M4A3-256/128 and M4A5-256/128	34
M4A3-256/160 and M4A3-256/192	36
M4A3-384	36
M4A3-512	36

Logic Allocator

Within the logic allocator, product terms are allocated to macrocells in “product term clusters.” The availability and distribution of product term clusters are automatically considered by the software as it fits functions within a PAL block. The size of a product term cluster has been optimized to provide high utilization of product terms, making complex functions using many product terms possible. Yet when few product terms are used, there will be a minimal number of unused—or wasted—product terms left over. The product term clusters available to each macrocell within a PAL block are shown in Tables 6 and 7.

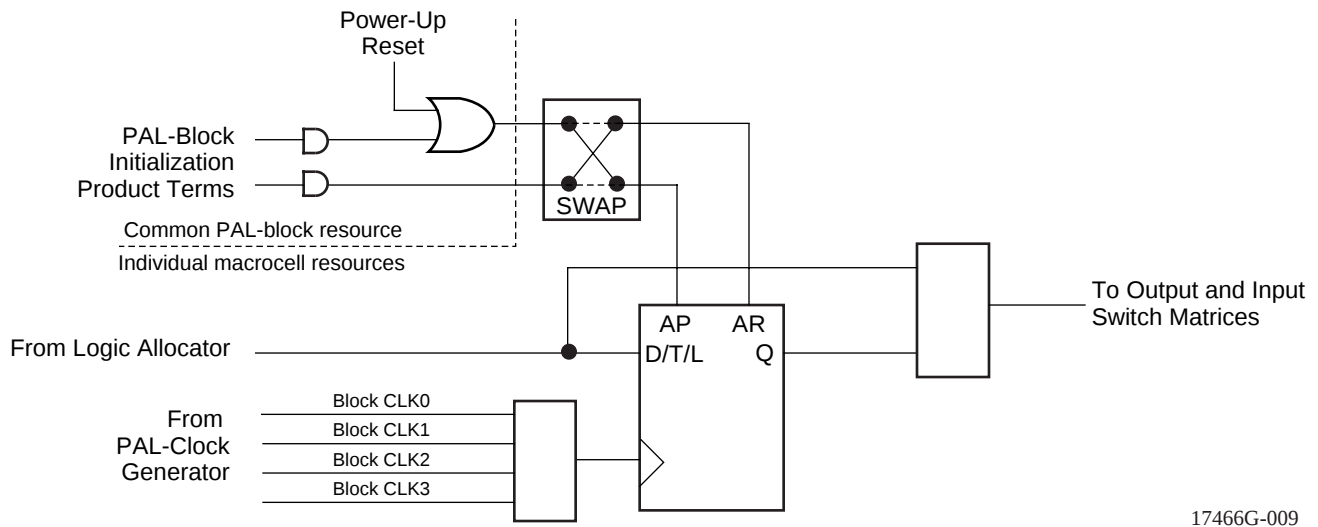
Each product term cluster is associated with a macrocell. The size of a cluster depends on the configuration of the associated macrocell. When the macrocell is used in synchronous mode (Figure 2a), the basic cluster has 4 product terms. When the associated macrocell is used in asynchronous mode (Figure 2b), the cluster has 2 product terms. Note that if the product term cluster is routed to a different macrocell, the allocator configuration is not determined by the mode of the macrocell actually being driven. The configuration is always set by the mode of the macrocell that the cluster will drive if not routed away, regardless of the actual routing.

In addition, there is an extra product term that can either join the basic cluster to give an extended cluster, or drive the second input of an exclusive-OR gate in the signal path. If included with the basic cluster, this provides for up to 20 product terms on a synchronous function that uses four extended 5-product-term clusters. A similar asynchronous function can have up to 18 product terms.

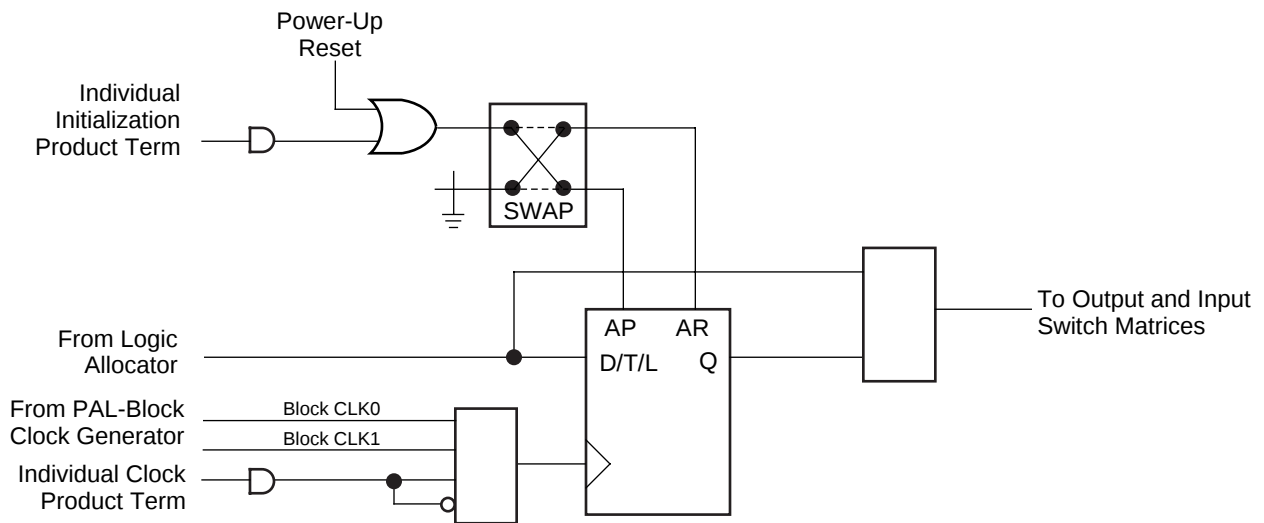
When the extra product term is used to extend the cluster, the value of the second XOR input can be programmed as a 0 or a 1, giving polarity control. The possible configurations of the logic allocator are shown in Figures 3 and 4.

Macrocell

The macrocell consists of a storage element, routing resources, a clock multiplexer, and initialization control. The macrocell has two fundamental modes: synchronous and asynchronous (Figure 5). The mode chosen only affects clocking and initialization in the macrocell.



a. Synchronous mode



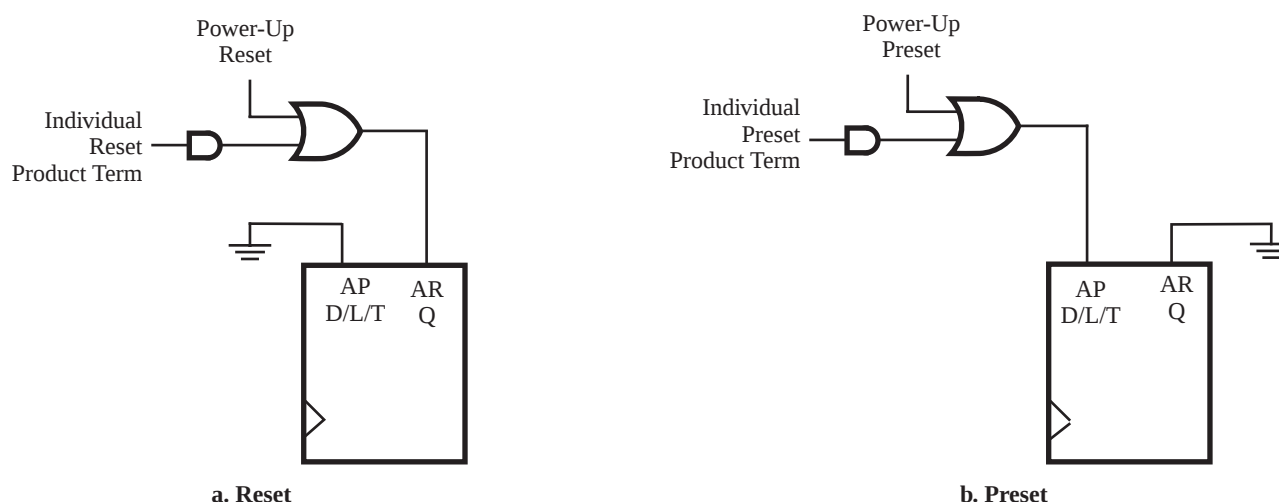
b. Asynchronous mode

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Figure 5. Macrocell

In either mode, a combinatorial path can be used. For combinatorial logic, the synchronous mode will generally be used, since it provides more product terms in the allocator.

A reset/preset swapping feature in each macrocell allows for reset and preset to be exchanged, providing flexibility. In asynchronous mode (Figure 8), a single individual product term is provided for initialization. It can be selected to control reset or preset.



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Figure 8. Asynchronous Mode Initialization Configurations

Note that the reset/preset swapping selection feature effects power-up reset as well. The initialization functionality of the flip-flops is illustrated in Table 9. The macrocell sends its data to the output switch matrix and the input switch matrix. The output switch matrix can route this data to an output if so desired. The input switch matrix can send the signal back to the central switch matrix as feedback.

Table 9. Asynchronous Reset/Preset Operation

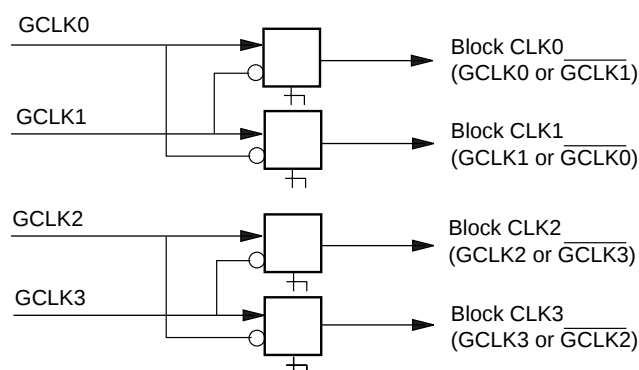
AR	AP	CLK/LE ¹	Q+
0	0	X	See Table 8
0	1	X	1
1	0	X	0
1	1	X	0

Note:

1. Transparent latch is unaffected by AR, AP

PAL Block Clock Generation

Each ispMACH 4A device has four clock pins that can also be used as inputs. These pins drive a clock generator in each PAL block (Figure 14). The clock generator provides four clock signals that can be used anywhere in the PAL block. These four PAL block clock signals can consist of a large number of combinations of the true and complement edges of the global clock signals. Table 14 lists the possible combinations.



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Figure 14. PAL Block Clock Generator¹

1. M4A(3,5)-32/32 and M4A(3,5)-64/32 have only two clock pins, GCLK0 and GCLK1. GCLK2 is tied to GCLK0, and GCLK3 is tied to GCLK1.

Table 14. PAL Block Clock Combinations¹

Block CLK0	Block CLK1	Block CLK2	Block CLK3
GCLK0	GCLK1	X	X
$\overline{\text{GCLK1}}$	GCLK1	X	X
GCLK0	$\overline{\text{GCLK0}}$	X	X
$\overline{\text{GCLK1}}$	$\overline{\text{GCLK0}}$	X	X
X	X	GCLK2 (GCLK0)	GCLK3 (GCLK1)
X	X	$\overline{\text{GCLK3}}$ ($\overline{\text{GCLK1}}$)	GCLK3 (GCLK1)
X	X	GCLK2 (GCLK0)	$\overline{\text{GCLK2}}$ ($\overline{\text{GCLK0}}$)
X	X	$\overline{\text{GCLK3}}$ (GCLK1)	$\overline{\text{GCLK2}}$ ($\overline{\text{GCLK0}}$)

Note:

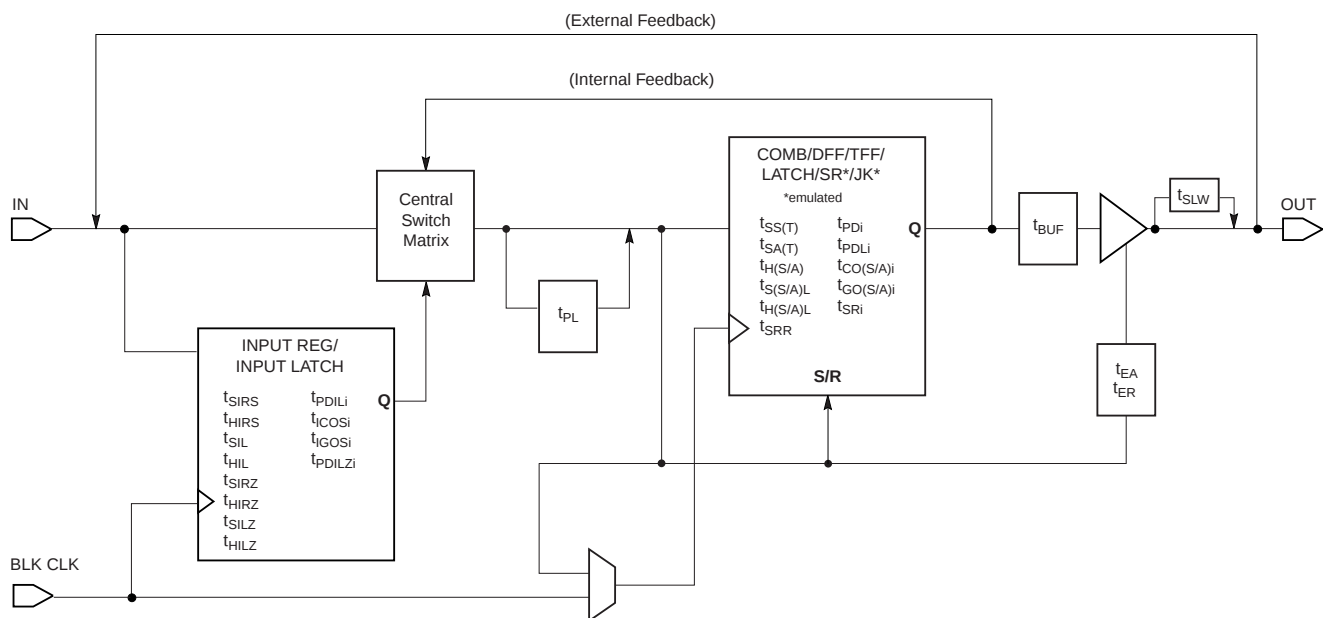
1. Values in parentheses are for the M4A(3,5)-32/32 and M4A(3,5)-64/32.

This feature provides high flexibility for partitioning state machines and dual-phase clocks. It also allows latches to be driven with either polarity of latch enable, and in a master-slave configuration.

ispMACH 4A TIMING MODEL

The primary focus of the ispMACH 4A timing model is to accurately represent the timing in a ispMACH 4A device, and at the same time, be easy to understand. This model accurately describes all combinatorial and registered paths through the device, making a distinction between internal feedback and external feedback. A signal uses internal feedback when it is fed back into the switch matrix or block without having to go through the output buffer. The input register specifications are also reported as internal feedback. When a signal is fed back into the switch matrix after having gone through the output buffer, it is using external feedback.

The parameter, t_{BUF} , is defined as the time it takes to go from feedback through the output buffer to the I/O pad. If a signal goes to the internal feedback rather than to the I/O pad, the parameter designator is followed by an “i”. By adding t_{BUF} to this internal parameter, the external parameter is derived. For example, $t_{PD} = t_{PDi} + t_{BUF}$. A diagram representing the modularized ispMACH 4A timing model is shown in Figure 15. Refer to the application note entitled *MACH 4 Timing and High Speed Design* for a more detailed discussion about the timing parameters.



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Figure 15. ispMACH 4A Timing Model

SPEEDLOCKING FOR GUARANTEED FIXED TIMING

The ispMACH 4A architecture allows allocation of up to 20 product terms to an individual macrocell with the assistance of an XOR gate without incurring additional timing delays.

The design of the switch matrix and PAL blocks guarantee a fixed pin-to-pin delay that is independent of the logic required by the design. Other competitive CPLDs incur serious timing delays as product terms expand beyond their typical 4 or 5 product term limits. Speed and SpeedLocking combine to give designs easy access to the performance required in today's designs.

IEEE 1149.1-COMPLIANT BOUNDARY SCAN TESTABILITY

All ispMACH 4A devices have boundary scan cells and are compliant to the IEEE 1149.1 standard. This allows functional testing of the circuit board on which the device is mounted through a serial scan path that can access all critical logic nodes. Internal registers are linked internally, allowing test data to be shifted in and loaded directly onto test nodes, or test node data to be captured and shifted out for verification. In addition, these devices can be linked into a board-level serial scan path for more complete board-level testing.

IEEE 1149.1-COMPLIANT IN-SYSTEM PROGRAMMING

Programming devices in-system provides a number of significant benefits including: rapid prototyping, lower inventory levels, higher quality, and the ability to make in-field modifications. All ispMACH 4A devices provide In-System Programming (ISP) capability through their Boundary ScanTest Access Ports. This capability has been implemented in a manner that ensures that the port remains compliant to the IEEE 1149.1 standard. By using IEEE 1149.1 as the communication interface through which ISP is achieved, customers get the benefit of a standard, well-defined interface.

ispMACH 4A devices can be programmed across the commercial temperature and voltage range. The PC-based ispVM™ software facilitates in-system programming of ispMACH 4A devices. ispVM takes the JEDEC file output produced by the design implementation software, along with information about the JTAG chain, and creates a set of vectors that are used to drive the JTAG chain. ispVM software can use these vectors to drive a JTAG chain via the parallel port of a PC. Alternatively, ispVM software can output files in formats understood by common automated test equipment. This equipment can then be used to program ispMACH 4A devices during the testing of a circuit board.

PCI COMPLIANT

ispMACH 4A devices in the -5/-55/-6/-65/-7/-10/-12 speed grades are compliant with the *PCI Local Bus Specification* version 2.1, published by the PCI Special Interest Group (SIG). The 5-V devices are fully PCI-compliant. The 3.3-V devices are mostly compliant but do not meet the PCI condition to clamp the inputs as they rise above V_{CC} because of their 5-V input tolerant feature.

SAFE FOR MIXED SUPPLY VOLTAGE SYSTEM DESIGNS

Both the 3.3-V and 5-V V_{CC} ispMACH 4A devices are safe for mixed supply voltage system designs. The 5-V devices will not overdrive 3.3-V devices above the output voltage of 3.3 V, while they accept inputs from other 3.3-V devices. The 3.3-V device will accept inputs up to 5.5 V. Both the 5-V and 3.3-V versions have the same high-speed performance and provide easy-to-use mixed-voltage design capability.

PULL UP OR BUS-FRIENDLY INPUTS AND I/Os

All ispMACH 4A devices have inputs and I/Os which feature the Bus-Friendly circuitry incorporating two inverters in series which loop back to the input. This double inversion weakly holds the input at its last driven logic state. While it is good design practice to tie unused pins to a known state, the Bus-Friendly input structure pulls pins away from the input threshold voltage where noise can cause high-frequency switching. At power-up, the Bus-Friendly latches are reset to a logic level “1.” For the circuit diagram, please refer to the document entitled *MACH Endurance Characteristics* on the Lattice Data Book CD-ROM or Lattice web site.

All ispMACH 4A devices have a programmable bit that configures all inputs and I/Os with either pull-up or Bus-Friendly characteristics. If the device is configured in pull-up mode, all inputs and I/O pins are

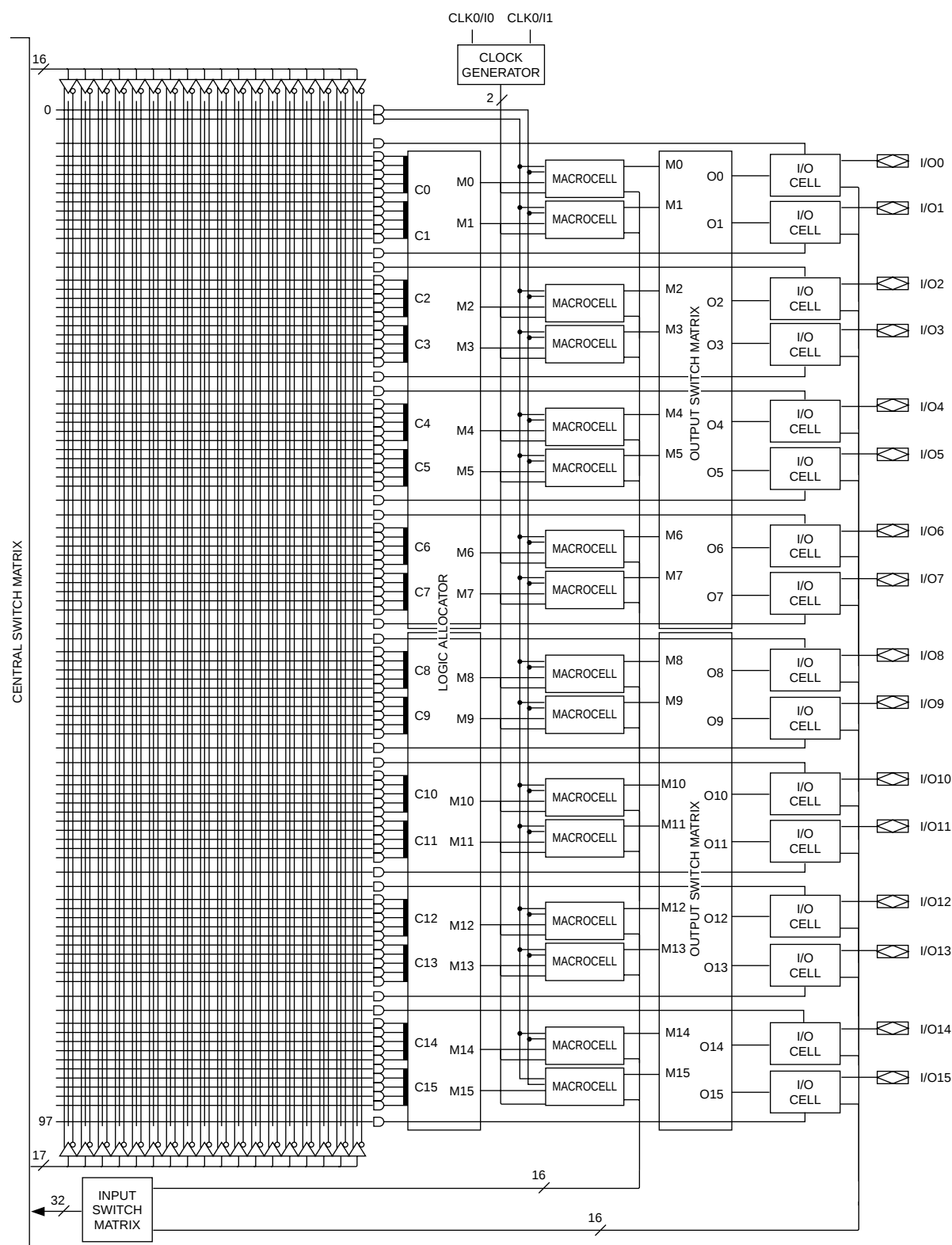
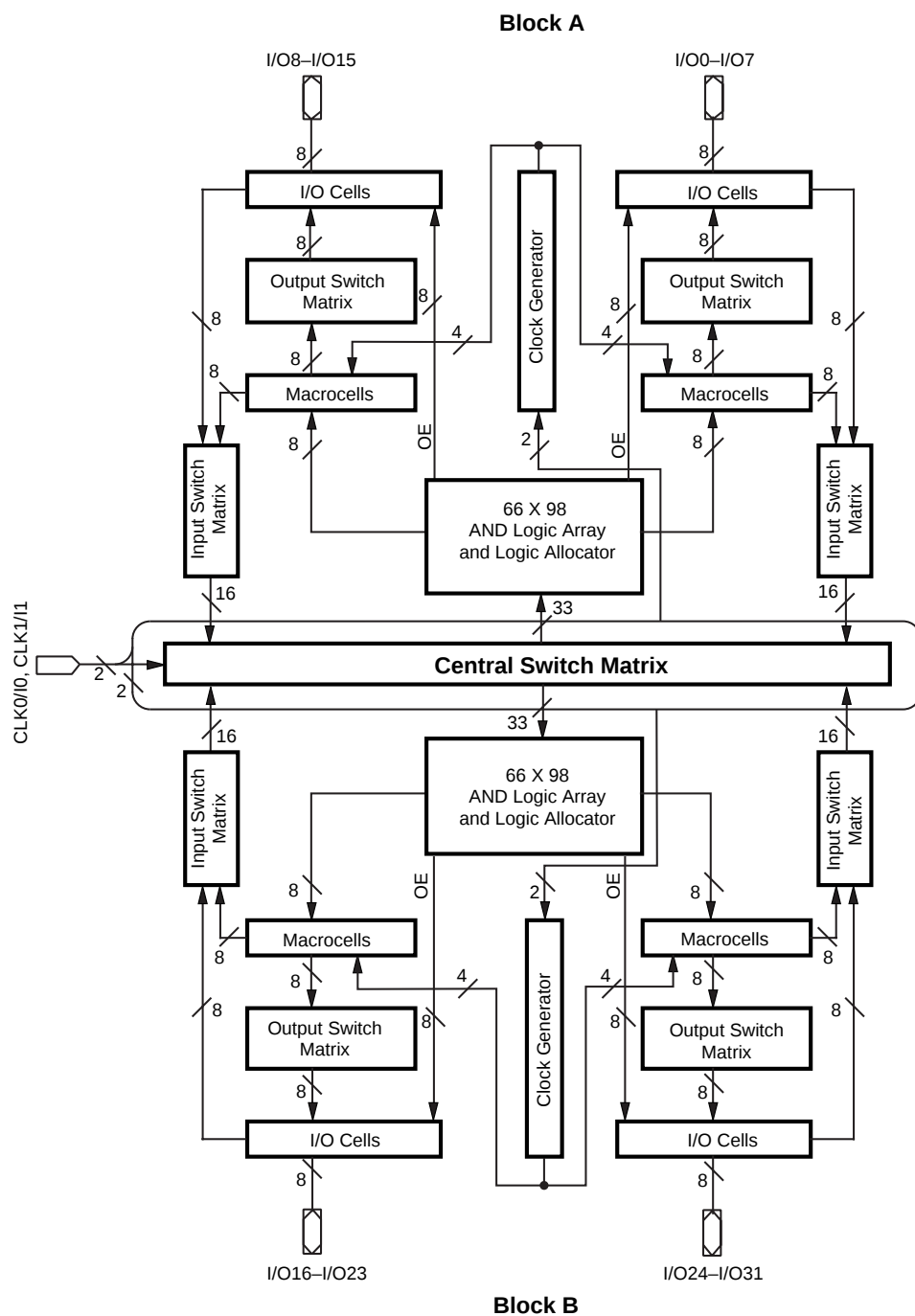


Figure 18. PAL Block for M4A (3,5)-32/32

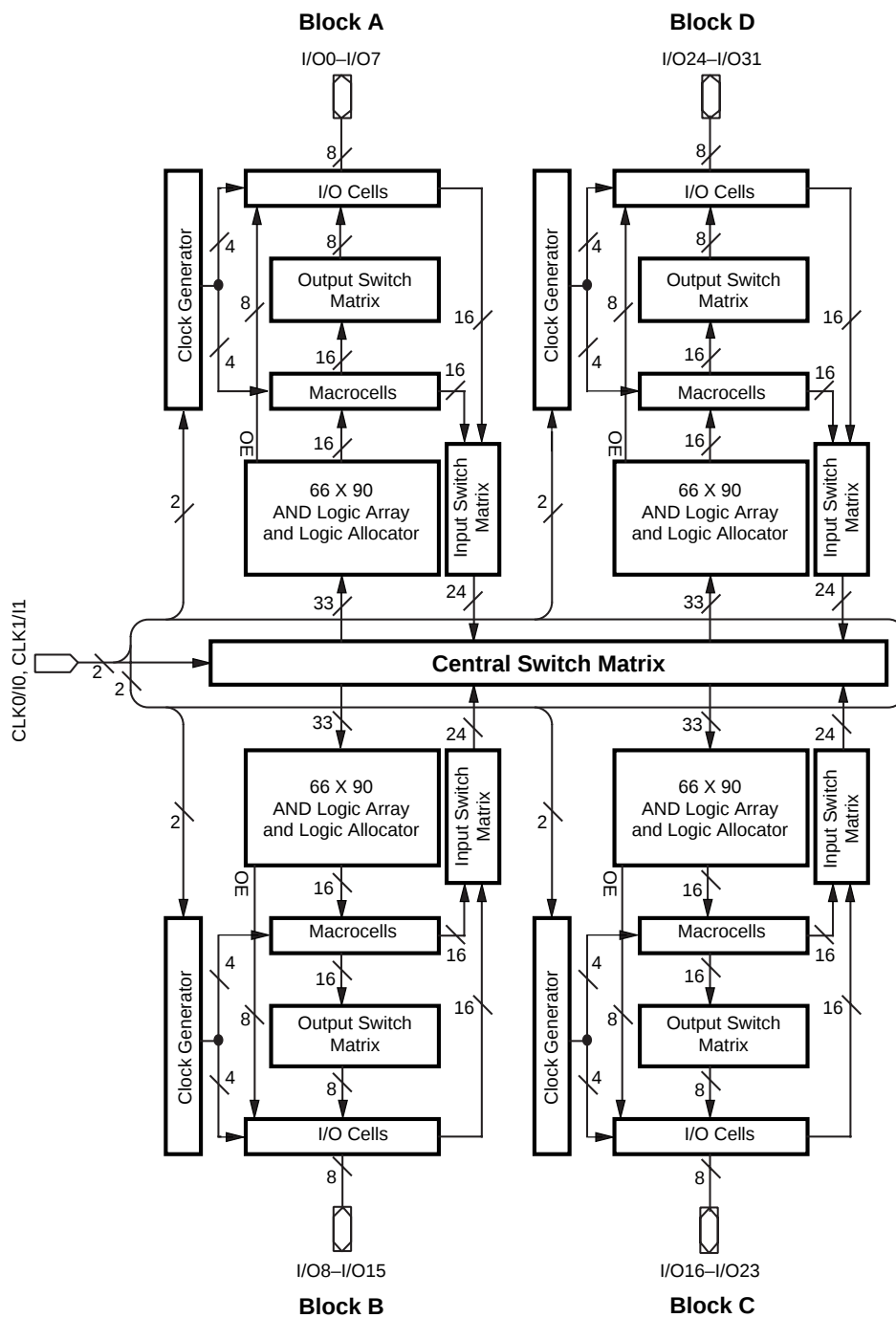
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BLOCK DIAGRAM – M4A(3,5)-32/32



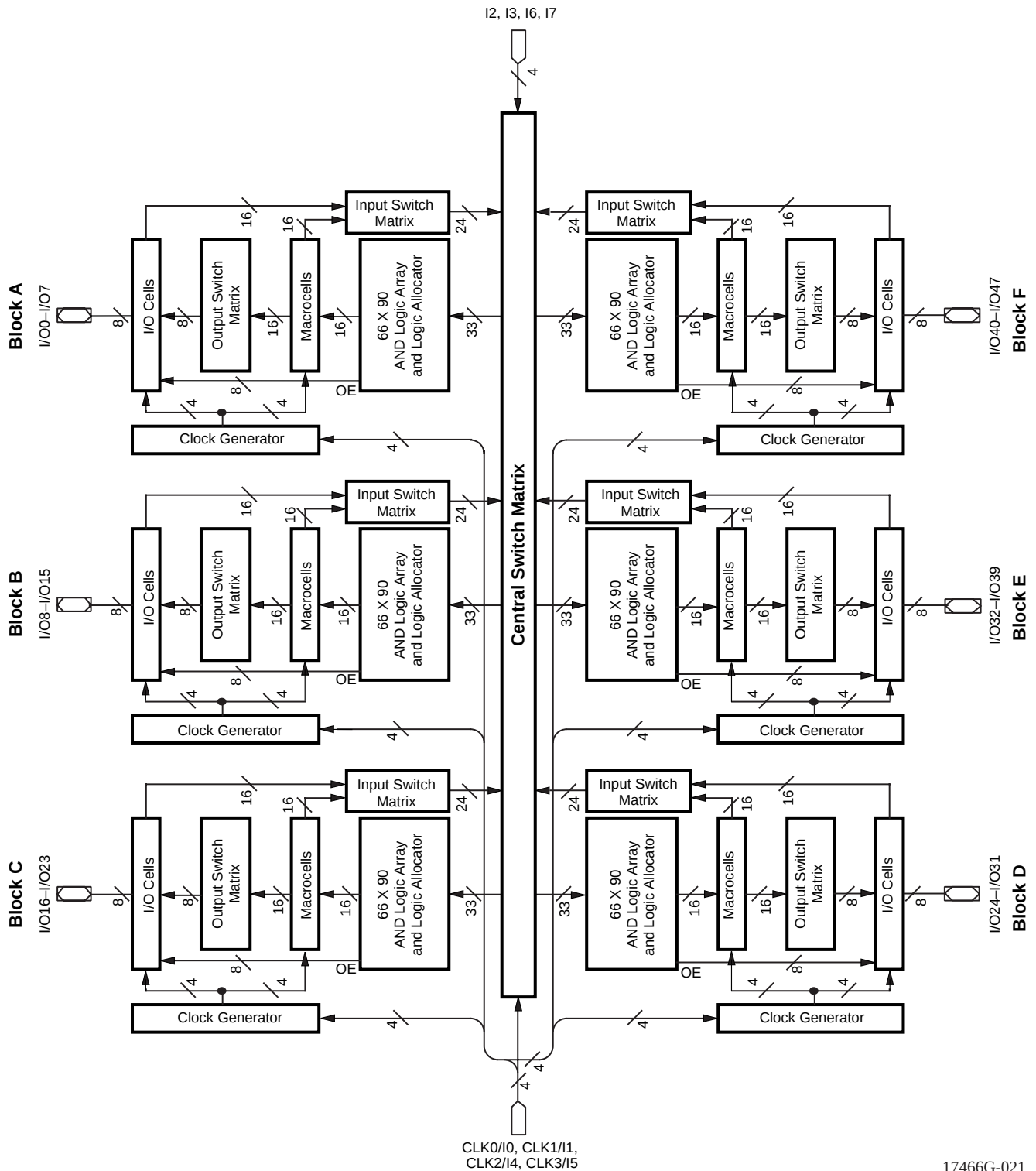
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BLOCK DIAGRAM – M4A(3,5)-64/32



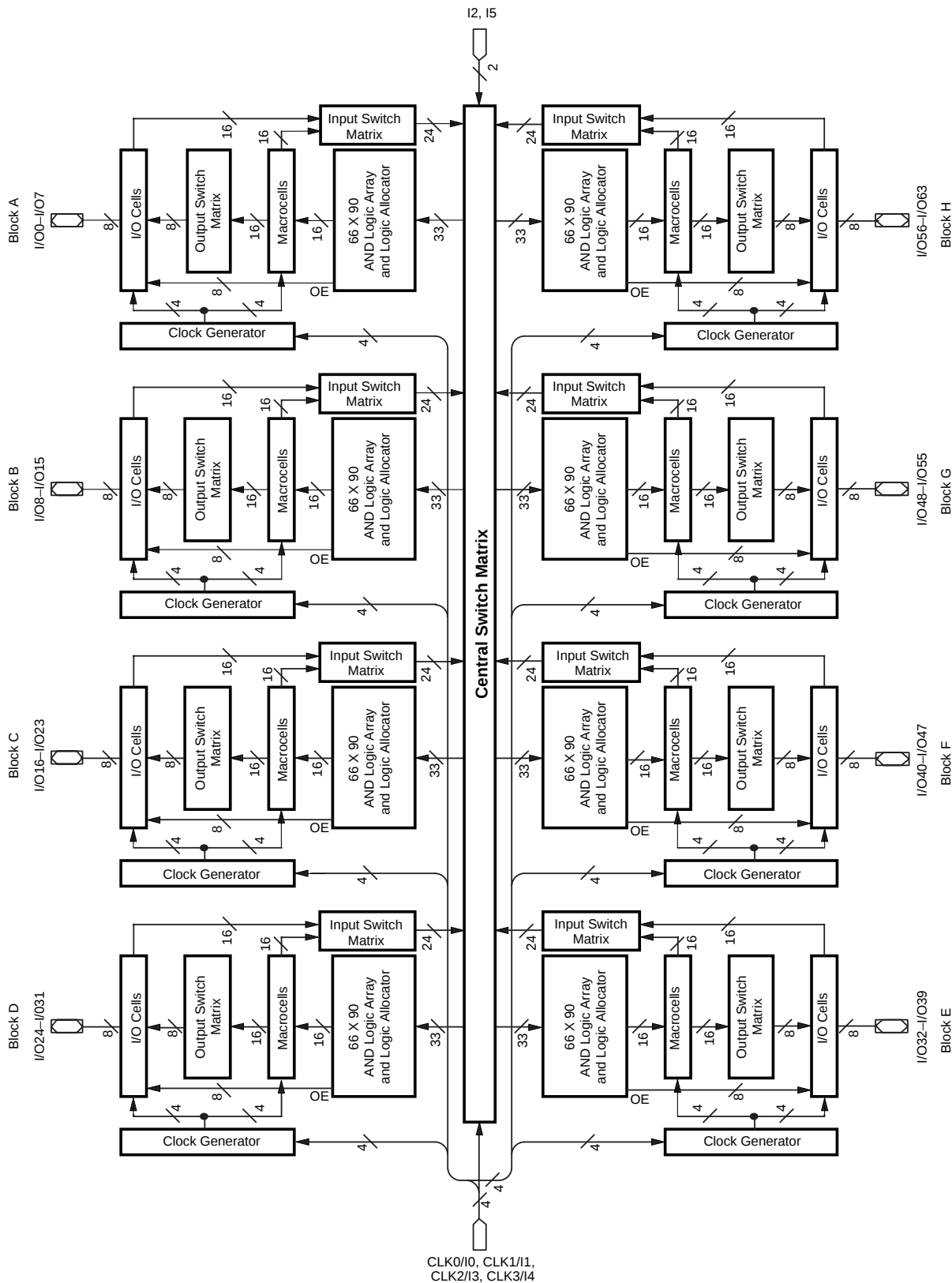
17466H-020

BLOCK DIAGRAM – M4A(3,5)-96/48



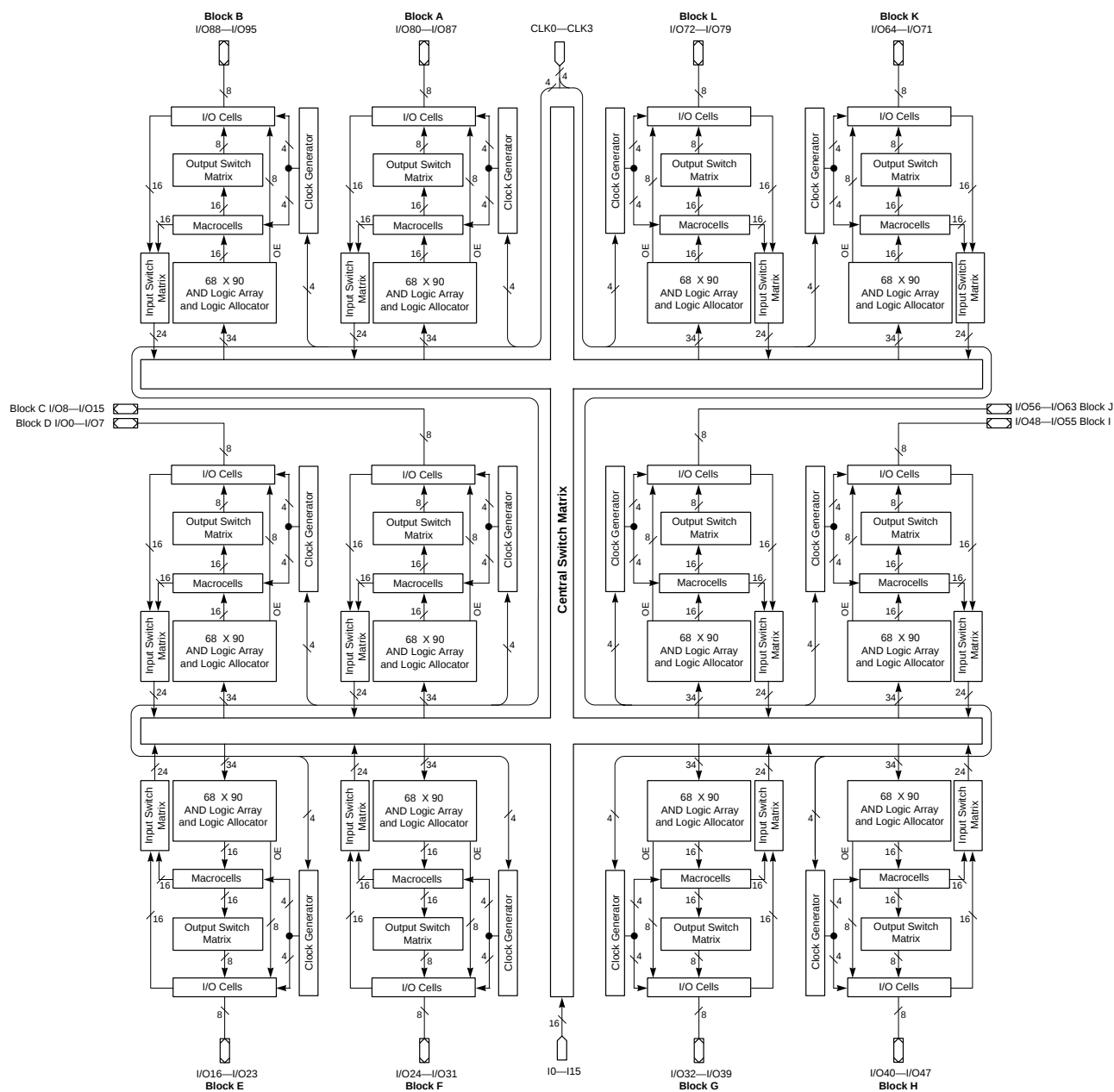
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BLOCK DIAGRAM – M4A(3,5)-128/64



17466H-022

BLOCK DIAGRAM – M4A(3,5)-192/96



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ABSOLUTE MAXIMUM RATINGS

M4A5

Storage Temperature. -65°C to +150°C
 Ambient Temperature
 with Power Applied. -55°C to +100°C
 Device Junction Temperature. +130°C
 Supply Voltage
 with Respect to Ground -0.5 V to +7.0 V
 DC Input Voltage -0.5 V to $V_{CC} + 0.5$ V
 Static Discharge Voltage 2000 V
 Latchup Current ($T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$) 200 mA

Stresses above those listed under Absolute Maximum Ratings may cause permanent device failure. Functionality at or above these limits is not implied. Exposure to Absolute Maximum Ratings for extended periods may affect device reliability.

OPERATING RANGES

Commercial (C) Devices

Ambient Temperature (T_A)
 Operating in Free Air. 0°C to $+70^\circ\text{C}$
 Supply Voltage (V_{CC})
 with Respect to Ground. +4.75 V to +5.25 V

Industrial (I) Devices

Ambient Temperature (T_A)
 Operating in Free Air. -40°C to $+85^\circ\text{C}$
 Supply Voltage (V_{CC})
 with Respect to Ground. +4.50 V to +5.5 V
Operating ranges define those limits between which the functionality of the device is guaranteed.

5-V DC CHARACTERISTICS OVER OPERATING RANGES

Parameter Symbol	Parameter Description	Test Conditions	Min	Typ	Max	Unit
V_{OH}	Output HIGH Voltage	$I_{OH} = -3.2$ mA, $V_{CC} = \text{Min}$, $V_{IN} = V_{IH}$ or V_{IL}	2.4			V
		$I_{OH} = -100$ μA , $V_{CC} = \text{Max}$, $V_{IN} = V_{IH}$ or V_{IL}		3.3	3.6	V
V_{OL}	Output LOW Voltage	$I_{OL} = 24$ mA, $V_{CC} = \text{Min}$, $V_{IN} = V_{IH}$ or V_{IL} (Note 1)			0.5	V
V_{IH}	Input HIGH Voltage	Guaranteed Input Logical HIGH Voltage for all Inputs (Note 2)	2.0			V
V_{IL}	Input LOW Voltage	Guaranteed Input Logical LOW Voltage for all Inputs (Note 2)			0.8	V
I_{IH}	Input HIGH Leakage Current	$V_{IN} = 5.25$ V, $V_{CC} = \text{Max}$ (Note 3)			10	μA
I_{IL}	Input LOW Leakage Current	$V_{IN} = 0$ V, $V_{CC} = \text{Max}$ (Note 3)			-10	μA
I_{OZH}	Off-State Output Leakage Current HIGH	$V_{OUT} = 5.25$ V, $V_{CC} = \text{Max}$, $V_{IN} = V_{IH}$ or V_{IL} (Note 3)			10	μA
I_{OZL}	Off-State Output Leakage Current LOW	$V_{OUT} = 0$ V, $V_{CC} = \text{Max}$, $V_{IN} = V_{IH}$ or V_{IL} (Note 3)			-10	μA
I_{SC}	Output Short-Circuit Current	$V_{OUT} = 0.5$ V, $V_{CC} = \text{Max}$ (Note 4)	-30		-160	mA

Notes:

1. Total I_{OL} for one PAL block should not exceed 64 mA.
2. These are absolute values with respect to device ground, and all overshoots due to system or tester noise are included.
3. I/O pin leakage is the worst case of I_{IL} and I_{OZL} (or I_{IH} and I_{OZH}).
4. Not more than one output should be shorted at a time and duration of the short-circuit should not exceed one second.
 $V_{OUT} = 0.5$ V has been chosen to avoid test problems caused by tester ground degradation.

ABSOLUTE MAXIMUM RATINGS

M4A3

Storage Temperature. -65°C to +150°C
 Ambient Temperature
 with Power Applied. -55°C to +100°C
 Device Junction Temperature. +130°C
 Supply Voltage
 with Respect to Ground. -0.5 V to +4.5 V
 DC Input Voltage. -0.5 V to 6.0 V
 Static Discharge Voltage. 2000 V
 Latchup Current ($T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$) 200 mA

Stresses above those listed under Absolute Maximum Ratings may cause permanent device failure. Functionality at or above these limits is not implied. Exposure to Absolute Maximum Ratings for extended periods may affect device reliability.

OPERATING RANGES

Commercial (C) Devices

Ambient Temperature (T_A)
 Operating in Free Air. 0°C to $+70^\circ\text{C}$
 Supply Voltage (V_{CC})
 with Respect to Ground. +3.0 V to +3.6 V

Industrial (I) Devices

Ambient Temperature (T_A)
 Operating in Free Air. -40°C to $+85^\circ\text{C}$
 Supply Voltage (V_{CC})
 with Respect to Ground. +3.0 V to +3.6 V

Operating ranges define those limits between which the functionality of the device is guaranteed.

3.3-V DC CHARACTERISTICS OVER OPERATING RANGES

Parameter Symbol	Parameter Description	Test Conditions		Min	Typ	Max	Unit
V_{OH}	Output HIGH Voltage	$V_{CC} = \text{Min}$ $V_{IN} = V_{IH}$ or V_{IL}	$I_{OH} = -100\ \mu\text{A}$	$V_{CC} - 0.2$			V
			$I_{OH} = -3.2\ \text{mA}$	2.4			V
V_{OL}	Output LOW Voltage	$V_{CC} = \text{Min}$ $V_{IN} = V_{IH}$ or V_{IL} (Note 1)	$I_{OL} = 100\ \mu\text{A}$			0.2	V
			$I_{OL} = 24\ \text{mA}$			0.5	V
V_{IH}	Input HIGH Voltage	Guaranteed Input Logical HIGH Voltage for all Inputs		2.0		5.5	V
V_{IL}	Input LOW Voltage	Guaranteed Input Logical LOW Voltage for all Inputs		-0.3		0.8	V
I_{IH}	Input HIGH Leakage Current	$V_{IN} = 3.6\ \text{V}$, $V_{CC} = \text{Max}$ (Note 2)				5	μA
I_{IL}	Input LOW Leakage Current	$V_{IN} = 0\ \text{V}$, $V_{CC} = \text{Max}$ (Note 2)				-5	μA
I_{OZH}	Off-State Output Leakage Current HIGH	$V_{OUT} = 3.6\ \text{V}$, $V_{CC} = \text{Max}$ $V_{IN} = V_{IH}$ or V_{IL} (Note 2)				5	μA
I_{OZL}	Off-State Output Leakage Current LOW	$V_{OUT} = 0\ \text{V}$, $V_{CC} = \text{Max}$ $V_{IN} = V_{IH}$ or V_{IL} (Note 2)				-5	μA
I_{SC}	Output Short-Circuit Current	$V_{OUT} = 0.5\ \text{V}$, $V_{CC} = \text{Max}$ (Note 3)		-15		-160	mA

Notes:

1. Total I_{OL} for one PAL block should not exceed 64 mA.
2. I/O pin leakage is the worst case of I_{IL} and I_{OZL} (or I_{IH} and I_{OZH}).
3. Not more than one output should be shorted at a time and duration of the short-circuit should not exceed one second.

Notes:

1. See "MACH Switching Test Circuit" document on the Literature Download page of the Lattice web site.
2. This parameter does not apply to flip-flops in the emulated mode since the feedback path is required for emulation.

ispMACH 4A TIMING PARAMETERS OVER OPERATING RANGES¹

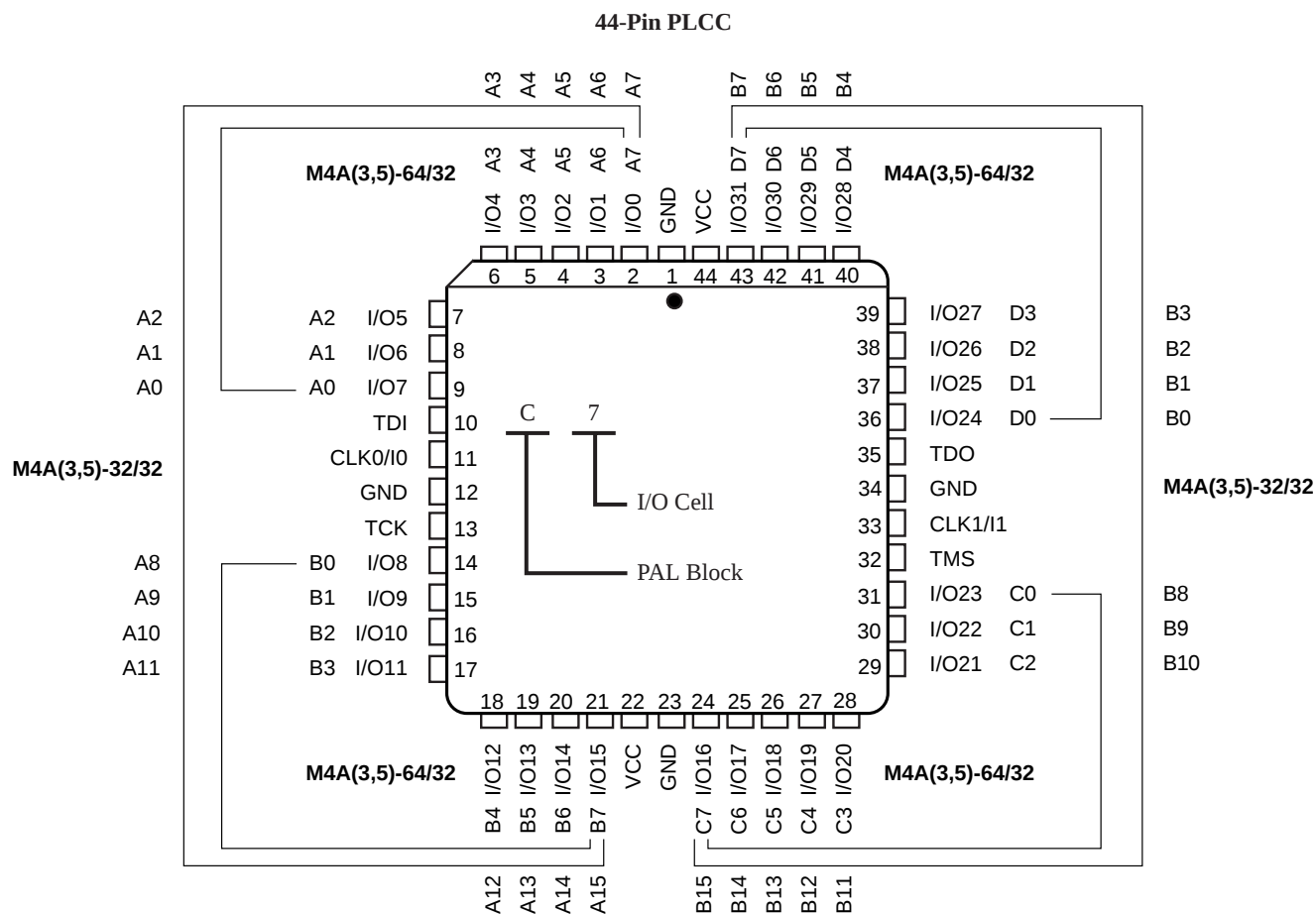
		-5		-55		-6		-65		-7		-10		-12		-14		Unit
		Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
Combinatorial Delay:																		
t _{PDi}	Internal combinatorial propagation delay		3.5		4.0		4.3		4.5		5.0		7.0		9.0		11.0	ns
t _{PD}	Combinatorial propagation delay		5.0		5.5		6.0		6.5		7.5		10.0		12.0		14.0	ns
Registered Delays:																		
t _{SS}	Synchronous clock setup time, D-type register	3.0		3.5		3.5		3.5		5.0		5.5		7.0		10.0		ns
t _{SST}	Synchronous clock setup time, T-type register	4.0		4.0		4.0		4.0		6.0		6.5		8.0		11.0		ns
t _{SA}	Asynchronous clock setup time, D-type register	2.5		2.5		2.5		3.0		3.5		4.0		5.0		8.0		ns
t _{SAT}	Asynchronous clock setup time, T-type register	3.0		3.0		3.0		3.5		4.5		5.0		6.0		9.0		ns
t _{HS}	Synchronous clock hold time	0.0		0.0		0.0		0.0		0.0		0.0		0.0		0.0		ns
t _{HA}	Asynchronous clock hold time	2.5		2.5		2.5		3.0		3.5		4.0		5.0		8.0		ns
t _{COsi}	Synchronous clock to internal output		2.5		2.5		2.8		3.0		3.0		3.0		3.5		3.5	ns
t _{COS}	Synchronous clock to output		4.0		4.0		4.5		5.0		5.5		6.0		6.5		6.5	ns
t _{COAi}	Asynchronous clock to internal output		5.0		5.0		5.0		5.0		6.0		8.0		10.0		12.0	ns
t _{COA}	Asynchronous clock to output		6.5		6.5		6.8		7.0		8.5		11.0		13.0		15.0	ns
Latched Delays:																		
t _{SSL}	Synchronous latch setup time	4.0		4.0		4.0		4.5		6.0		7.0		8.0		10.0		ns
t _{SAL}	Asynchronous latch setup time	3.0		3.0		3.5		3.5		4.0		4.0		5.0		8.0		ns
t _{HSL}	Synchronous latch hold time	0.0		0.0		0.0		0.0		0.0		0.0		0.0		0.0		ns
t _{HAL}	Asynchronous latch hold time	3.0		3.0		3.5		3.5		4.0		4.0		5.0		8.0		ns
t _{PDLi}	Transparent latch to internal output		5.5		5.5		5.8		6.0		7.5		9.0		11.0		12.0	ns
t _{PDL}	Propagation delay through transparent latch to output		7.0		7.0		7.5		8.0		10.0		12.0		14.0		15.0	ns
t _{GOSi}	Synchronous gate to internal output		3.0		3.0		3.0		3.0		3.5		4.5		7.0		8.0	ns
t _{GOS}	Synchronous gate to output		4.5		4.5		4.8		5.0		6.0		7.5		10.0		11.0	ns
t _{GOAi}	Asynchronous gate to internal output		6.0		6.0		6.0		6.0		8.5		10.0		13.0		15.0	ns
t _{GOA}	Asynchronous gate to output		7.5		7.5		7.8		8.0		11.0		13.0		16.0		18.0	ns
Input Register Delays:																		
t _{SIRS}	Input register setup time	1.5		1.5		2.0		2.0		2.0		2.0		2.0		2.0		ns
t _{HIRS}	Input register hold time	2.5		2.5		3.0		3.0		3.0		3.0		3.0		4.0		ns
t _{ICOSi}	Input register clock to internal feedback		3.0		3.0		3.0		3.0		3.5		4.5		6.0		6.0	ns
Input Latch Delays:																		
t _{SIL}	Input latch setup time	1.5		1.5		1.5		2.0		2.0		2.0		2.0		2.0		ns
t _{HIL}	Input latch hold time	2.5		2.5		2.5		3.0		3.0		3.0		3.0		4.0		ns
t _{IGOSi}	Input latch gate to internal feedback		3.5		3.5		3.8		4.0		4.0		4.0		4.0		5.0	ns
t _{PDILi}	Transparent input latch to internal feedback		1.5		1.5		1.5		1.5		2.0		2.0		2.0		2.0	ns

ispMACH 4A TIMING PARAMETERS OVER OPERATING RANGES¹

		-5		-55		-6		-65		-7		-10		-12		-14		Unit
		Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
Input Register Delays with ZHT Option:																		
t _{SIRZ}	Input register setup time - ZHT	6.0		6.0		6.0		6.0		6.0		6.0		6.0		6.0		ns
t _{HIRZ}	Input register hold time - ZHT	0.0		0.0		0.0		0.0		0.0		0.0		0.0		0.0		ns
Input Latch Delays with ZHT Option:																		
t _{SILZ}	Input latch setup time - ZHT	6.0		6.0		6.0		6.0		6.0		6.0		6.0		6.0		ns
t _{HILZ}	Input latch hold time - ZHT	0.0		0.0		0.0		0.0		0.0		0.0		0.0		0.0		ns
t _{PDIL} Z _i	Transparent input latch to internal feedback - ZHT		6.0		6.0		6.0		6.0		6.0		6.0		6.0		6.0	ns
Output Delays:																		
t _{BUF}	Output buffer delay		1.5		1.5		1.8		2.0		2.5		3.0		3.0		3.0	ns
t _{SLW}	Slow slew rate delay adder		2.5		2.5		2.5		2.5		2.5		2.5		2.5		2.5	ns
t _{EA}	Output enable time		7.5		7.5		8.5		8.5		9.5		10.0		12.0		15.0	ns
t _{ER}	Output disable time		7.5		7.5		8.5		8.5		9.5		10.0		12.0		15.0	ns
Power Delay:																		
t _{PL}	Power-down mode delay adder		2.5		2.5		2.5		2.5		2.5		2.5		2.5		2.5	ns
Reset and Preset Delays:																		
t _{SRI}	Asynchronous reset or preset to internal register output		7.5		7.7		8.0		8.0		9.5		11.0		13.0		16.0	ns
t _{SR}	Asynchronous reset or preset to register output		9.0		9.2		10.0		10.0		12.0		14.0		16.0		19.0	ns
t _{SRR}	Asynchronous reset and preset register recovery time	7.0		7.0		7.5		7.5		8.0		8.0		10.0		15.0		ns
t _{SRW}	Asynchronous reset or preset width	7.0		7.0		8.0		8.0		10.0		10.0		12.0		15.0		ns
Clock/LE Width:																		
t _{WLS}	Global clock width low	2.0		2.0		2.5		2.5		3.0		4.0		5.0		6.0		ns
t _{WHS}	Global clock width high	2.0		2.0		2.5		2.5		3.0		4.0		5.0		6.0		ns
t _{WLA}	Product term clock width low	3.0		3.0		3.5		3.5		4.0		5.0		8.0		9.0		ns
t _{WHA}	Product term clock width high	3.0		3.0		3.5		3.5		4.0		5.0		8.0		9.0		ns
t _{GWS}	Global gate width low (for low transparent) or high (for high transparent)	4.0		4.0		4.5		4.5		5.0		5.0		6.0		6.0		ns
t _{GWA}	Product term gate width low (for low transparent) or high (for high transparent)	4.0		4.0		4.5		4.5		5.0		5.0		6.0		9.0		ns
t _{WIRL}	Input register clock width low	3.0		3.0		3.5		3.5		4.0		5.0		6.0		6.0		ns
t _{WIRH}	Input register clock width high	3.0		3.0		3.5		3.5		4.0		5.0		6.0		6.0		ns
t _{WIL}	Input latch gate width	4.0		4.0		4.5		4.5		5.0		5.0		6.0		6.0		ns

44-PIN PLCC CONNECTION DIAGRAM (M4A(3,5)-32/32 AND M4A(3,5)-64/32)

Top View



17466G-026

PIN DESIGNATIONS

CLK/I = Clock or Input

GND = Ground

I/O = Input/Output

V_{CC} = Supply Voltage

TDI = Test Data In

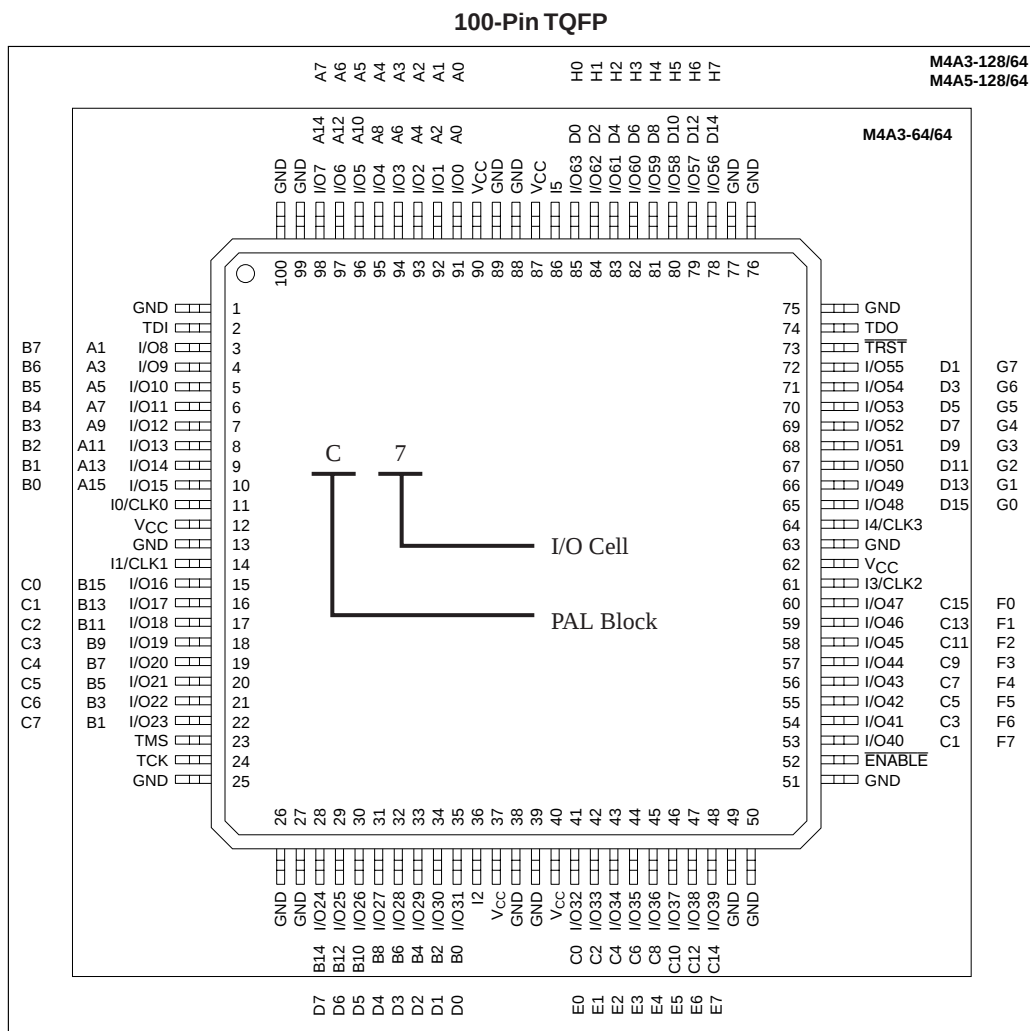
TCK = Test Clock

TMS = Test Mode Select

TDO = Test Data Out

100-PIN TQFP CONNECTION DIAGRAM (M4A3-64/64 AND M4A(3,5)-128/64)

Top View



PIN DESIGNATIONS

CLK/I = Clock or Input

GND = Ground

I = Input

I/O = Input/Output

V_{CC} = Supply Voltage

TDI = Test Data In

TCK = Test Clock

TMS = Test Mode Select

TDO = Test Data Out

TRST = Test Reset

ENABLE = Program

256-BALL fpBGA CONNECTION DIAGRAM (M4A3-384/192)

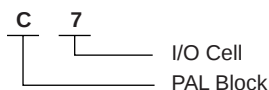
Bottom View

256-Ball fpBGA

	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	
A	I/O175 FX7	I/O181 GX5	I/O180 GX4	I/O177 GX1	I/O166 EX6	I/O164 EX4	I/O191 HX7	I/O186 HX2	I/O1 A1	I/O3 A3	CLK0	I/O25 D1	I/O29 D5	I/O31 D7	I/O10 B2	I/O12 B4	A
B	I/O173 FX5	I/O174 FX6	I/O182 GX6	I/O179 GX3	I/O167 EX7	I/O165 EX5	I/O160 EX0	I/O187 HX3	I/O0 A0	I/O5 A5	I/O7 A7	I/O26 D2	I/O8 B0	I/O11 B3	I/O13 B5	N/C	B
C	I/O171 FX3	I/O172 FX4	N/C	I/O183 GX7	I/O178 GX2	I/O162 EX2	I/O163 EX3	I/O189 HX5	I/O184 HX0	I/O6 A6	I/O28 D4	I/O30 D6	I/O15 B7	I/O14 B6	TDI	I/O23 C7	C
D	I/O150 CX6	I/O151 CX7	TDO	GND	GND	VCC	GND	VCC	GND	GND	VCC	GND	VCC	I/O9 B1	I/O22 C6	I/O21 C5	D
E	I/O148 CX4	N/C	I/O170 FX2	VCC	I/O168 FX0	169 FX1	I/O190 HX6	CLK3	I/O188 HX4	I/O2 A2	I/O24 D0	N/C	GND	I/O20 C4	I/O19 C3	I/O47 F7	E
F	I/O144 CX0	I/O149 CX5	I/O147 CX3	GND	I/O146 CX2	I/O145 CX1	I/O176 GX0	I/O161 EX1	I/O185 HX1	I/O4 A4	I/O27 D3	I/O18 C2	VCC	I/O16 C0	I/O46 F6	I/O45 F5	F
G	I/O155 DX3	I/O158 DX6	I/O157 DX5	VCC	I/O156 DX4	I/O159 DX7	VCC	GND	GND	VCC	I/O17 C1	I/O44 F4	GND	I/O42 F2	I/O41 F1	I/O39 E7	G
H	I/O152 DX0	I/O154 DX2	I/O153 DX1	GND	I/O128 AX0	I/O129 AX1	GND	VCC	VCC	GND	I/O43 F3	I/O40 F0	VCC	I/O36 E4	I/O35 E3	I/O34 E2	H
J	I/O130 AX2	I/O131 AX3	I/O132 AX4	GND	I/O134 AX6	I/O133 AX5	GND	VCC	VCC	GND	I/O38 E6	I/O37 E5	GND	I/O57 H1	I/O56 H0	I/O58 H2	J
K	I/O135 AX7	I/O136 BX0	I/O137 BX1	VCC	I/O139 BX3	I/O138 BX2	VCC	GND	GND	VCC	I/O33 E1	I/O32 E0	VCC	I/O63 H7	I/O62 H6	I/O48 G0	K
L	I/O140 BX4	I/O141 BX5	I/O143 BX7	GND	I/O114 O2	I/O142 BX6	I/O98 M2	I/O91 L3	I/O67 I3	I/O69 I5	I/O60 H4	I/O59 H3	GND	I/O51 G3	I/O52 G4	I/O49 G1	L
M	I/O112 O0	I/O113 O1	I/O115 O3	GND	I/O123 P3	I/O121 P1	I/O100 M4	I/O90 L2	I/O66 I2	I/O80 K0	I/O83 K3	I/O61 H5	VCC	I/O76 J4	I/O55 G7	I/O50 G2	M
N	I/O116 O4	I/O117 O5	I/O119 O7	VCC	GND	VCC	GND	VCC	GND	GND	VCC	GND	GND	TCK	I/O72 J0	I/O53 G5	N
P	I/O118 O6	I/O109 N5	I/O110 N6	I/O111 N7	I/O124 P4	I/O122 P2	I/O101 M5	I/O89 L1	I/O93 L5	I/O94 L6	I/O71 I7	I/O84 K4	I/O87 K7	TMS	I/O73 J1	I/O54 G6	P
R	I/O108 N4	I/O107 N3	I/O104 N0	I/O127 P7	I/O120 P0	I/O102 M6	I/O99 M3	I/O96 M0	I/O92 L4	I/O64 I0	I/O68 I4	I/O81 K1	I/O85 K5	I/O79 J7	I/O75 J3	I/O74 J2	R
T	I/O106 N2	I/O105 N1	I/O126 P6	I/O125 P5	I/O103 M7	CLK2	I/O97 M1	I/O88 L0	CLK1	I/O95 L7	I/O65 I1	I/O70 I6	I/O82 K2	I/O86 K6	I/O78 J6	I/O77 J5	T
	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	

PIN DESIGNATIONS

CLK = Clock
 GND = Ground
 I = Input
 I/O = Input/Output
 N/C = No Connect
 VCC = Supply Voltage
 TDI = Test Data In
 TCK = Test Clock
 TMS = Test Mode Select
 TDO = Test Data Out



m4a3.384.192_256bga

388-BALL fpBGA CONNECTION DIAGRAM (M4A3-512/256)

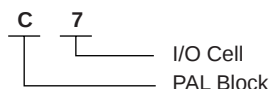
Bottom View

388-Ball fpBGA

	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	
A	GND	I/O243 OX3	I/O240 OX0	I/O241 OX1	I/O236 NX4	I/O231 MX7	I/O228 MX4	I/O226 MX2	I/O255 PX7	I/O251 PX3	I/O248 PX0	I/O0 A0	I/O5 A5	I/O6 A6	I/O27 D3	I/O30 D6	I/O17 C1	I/O22 C6	I/O8 B0	I/O10 B2	N/C	GND	A
B	N/C	GND	I/O245 OX5	I/O242 OX2	I/O238 NX6	I/O234 NX2	I/O232 NX0	I/O229 MX5	I/O224 MX0	I/O253 PX5	I/O249 PX1	I/O2 A2	CLK0	I/O26 D2	I/O29 D5	I/O31 D7	I/O20 C4	I/O9 B1	I/O12 B4	I/O13 B5	GND	TDI	B
C	I/O213 KX5	TDO	GND	I/O247 OX7	I/O244 OX4	I/O239 NX7	I/O235 NX3	I/O230 MX6	I/O227 MX3	CLK3	I/O250 PX2	I/O1 A1	I/O7 A7	I/O25 D1	I/O16 C0	I/O18 C2	I/O23 C7	I/O11 B3	I/O15 B7	GND	I/O47 F7	I/O44 F4	C
D	I/O210 KX2	I/O212 KX4	I/O215 KX7	GND	I/O246 OX6	VCC	I/O237 NX5	I/O233 NX1	VCC	I/O254 PX6	VCC	I/O3 A3	I/O24 D0	VCC	I/O19 C3	I/O21 C5	VCC	I/O14 B6	GND	I/O46 F6	I/O43 F3	I/O41 F1	D
E	I/O207 JX7	I/O209 KX1	I/O211 KX3	I/O214 KX6															I/O45 F5	I/O42 F2	I/O40 F0	I/O54 G6	E
F	I/O203 JX3	I/O205 JX5	I/O208 KX0	VCC															VCC	I/O55 G7	I/O52 G4	I/O50 G2	F
G	I/O200 JX0	I/O202 JX2	I/O204 JX4	I/O206 JX6			VCC	VCC	N/C	I/O225 MX1	I/O252 PX4	I/O4 A4	I/O28 D4	N/C	VCC	VCC			I/O53 G5	I/O51 G3	I/O49 G1	I/O39 E7	G
H	I/O221 LX5	I/O222 LX6	I/O223 LX7	I/O201 JX1			VCC	N/C	GND	GND	GND	GND	GND	GND	N/C	VCC			I/O48 G0	I/O38 E6	I/O37 E5	I/O36 E4	H
J	I/O218 LX2	I/O219 LX3	I/O220 LX4	VCC			N/C	GND	GND	GND	GND	GND	GND	GND	GND	N/C			VCC	I/O35 E3	I/O34 E2	I/O32 E0	J
K	I/O197 IX5	I/O198 IX6	I/O199 IX7	I/O216 LX0			I/O217 LX1	GND	GND	GND	GND	GND	GND	GND	GND	I/O33 E1			I/O63 H7	I/O62 H6	I/O61 H5	I/O60 H4	K
L	I/O192 IX0	I/O194 IX2	I/O195 IX3	I/O196 IX4			I/O193 IX1	GND	GND	GND	GND	GND	GND	GND	GND	I/O58 H2			VCC	I/O59 H3	I/O57 H1	I/O56 H0	L
M	I/O184 HX0	I/O185 HX1	I/O187 HX3	VCC			I/O186 HX2	GND	GND	GND	GND	GND	GND	GND	GND	I/O69 I5			I/O67 I3	I/O65 I1	I/O66 I2	I/O64 I0	M
N	I/O188 HX4	I/O189 HX5	I/O191 HX7	I/O190 HX6			I/O162 EX2	GND	GND	GND	GND	GND	GND	GND	GND	I/O89 L1			I/O88 L0	I/O71 I7	I/O70 I6	I/O68 I4	N
P	I/O160 EX0	I/O161 EX1	I/O163 EX3	VCC			N/C	GND	GND	GND	GND	GND	GND	GND	GND	N/C			VCC	I/O92 L4	I/O91 L3	I/O90 L2	P
R	I/O164 EX4	I/O165 EX5	I/O166 EX6	I/O177 GX1			VCC	N/C	GND	GND	GND	GND	GND	GND	N/C	VCC			I/O74 J2	I/O95 L7	I/O94 L6	I/O93 L5	R
T	I/O167 EX7	I/O176 GX0	I/O179 GX3	I/O181 GX5			VCC	VCC	N/C	I/O152 DX0	I/O131 AX3	I/O122 P2	I/O98 M2	N/C	VCC	VCC			I/O78 J6	I/O76 J4	I/O73 J1	I/O72 J0	T
U	I/O178 GX2	I/O180 GX4	I/O183 GX7	VCC															VCC	I/O80 K0	I/O77 J5	I/O75 J3	U
V	I/O182 GX6	N/C	I/O169 FX1	I/O172 FX4															I/O86 K6	I/O83 K3	I/O81 K1	I/O79 J7	V
W	I/O168 FX0	I/O170 FX2	I/O173 FX5	GND	I/O143 BX7	VCC	I/O150 CX6	I/O145 CX1	VCC	I/O153 DX1	I/O123 P3	VCC	I/O96 M0	VCC	I/O104 N0	I/O111 N7	VCC	I/O119 O7	GND	I/O87 K7	I/O84 K4	I/O82 K2	W
Y	I/O171 FX3	I/O174 FX6	GND	I/O141 BX5	I/O138 BX2	I/O136 BX0	I/O147 CX3	I/O158 DX6	I/O156 DX4	CLK2	I/O132 AX4	I/O121 P1	I/O125 P5	I/O99 M3	I/O101 M5	I/O106 N2	I/O110 N6	I/O115 O3	I/O118 O6	GND	TMS	I/O85 K5	Y
AA	I/O175 FX7	GND	I/O142 BX6	I/O140 BX4	I/O151 CX7	I/O149 CX5	I/O144 CX0	I/O157 DX5	I/O154 DX2	I/O134 AX6	I/O130 AX2	I/O128 AX0	CLK1	I/O127 P7	I/O100 M4	I/O103 M7	I/O108 N4	I/O109 N5	I/O113 O1	I/O116 O4	GND	TCK	AA
AB	GND	N/C	I/O139 BX3	I/O137 BX1	I/O148 CX4	I/O146 CX2	I/O159 DX7	I/O155 DX3	I/O135 AX7	I/O133 AX5	I/O129 AX1	I/O120 P0	I/O124 P4	I/O126 P6	I/O97 M1	I/O102 M6	I/O105 N1	I/O107 N3	I/O112 O0	I/O114 O2	I/O117 O5	GND	AB

PIN DESIGNATIONS

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 GND = Ground
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m4a3.512.256_388bga